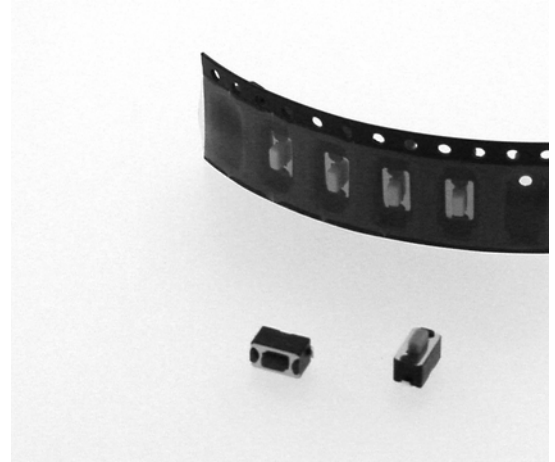
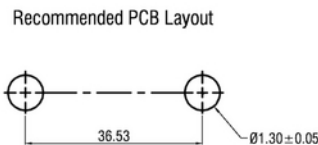
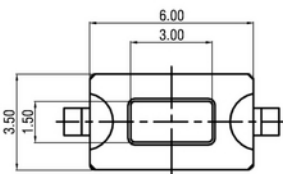


Technische Daten / Technical Data

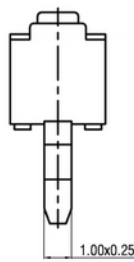
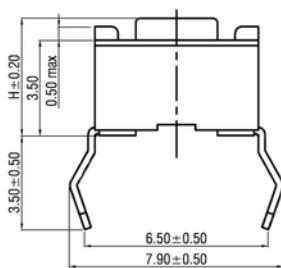
Gehäuse/Abdeckung/Hebel	Thermoplastischer Kunststoff, nach UL94 V-0 Rostfreier Stahl Thermoplastischer Kunststoff, nach UL94 V-0
Case/Cover/Actuator	Thermoplastic, rated UL94 V-0 Stainless Steel Thermoplastic, rated UL94 V-0
Kontaktmaterial	Kupferlegierung, versilbert
Contact Material	Silver plated copper alloy
Kontaktbelastbarkeit	50mA, 12V _{DC}
Contact Rating	50mA, 12V _{DC}
Lötbarkeit	IEC 60512-12A
Solderability	IEC 60512-12A
Durchgangswiderstand	< 100mΩ
Contact Resistance	< 100mΩ
Isolationswiderstand	> 10 ⁸ Ω
Insulation Resistance	> 10 ⁸ Ω
Spannungsfestigkeit	250V _{AC}
Test Voltage	250V _{AC}
Temperaturbereich	-25°C ... +70°C
Temperature Range	-25°C ... +70°C
Elektrische Lebensdauer	50.000 Zyklen (Type 30, 50) 30.000 Zyklen (Type 40, 60)
Electrical Life	50,000 cycles (Type 30, 50) 30,000 Zyklen (Type 40, 60)
Verarbeitung	Einlöt-Versionen: Wellenlötverfahren
Processing	SMT-Versionen: Kurzes Reflow-Lötverfahren
	Solder-In versions: Wave soldering
	SMT versions: Fast Profile Reflow-soldering
Max. Tasterbelastung	3kg vertikal für 15s
Max. Switching Force	3kg vertically for 15s



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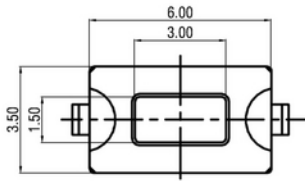
Circuit Diagram



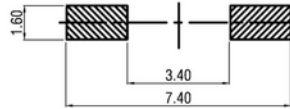
Series	Type	Height*	Operating Force*	Packing
508	1 1 Einlöt Through-Hole	1 1 H=4,3mm 2 H=5,0mm	40 30 160g±50 (braun) 160g±50 (brown) 40 260g±50 (rot) 260g±50 (red) 50 320g±80 (lachsfarben) 320g±80 (salmon) 70 520g±130 (gelb) 520g±130 (yellow)	ST ST

508

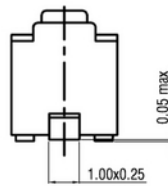
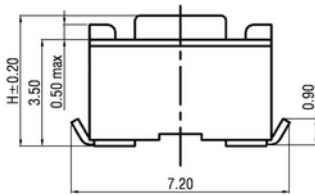
Taster - Einlöt / SMT - schmale Bauform
Tact Switches - Solder-in / SMT - Slim Body



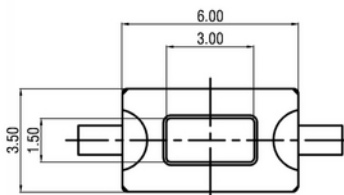
Recommended PCB Layout



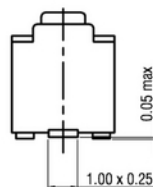
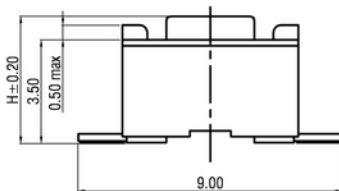
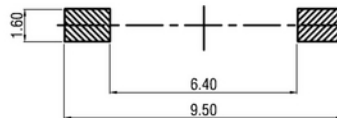
Circuit Diagram



Circuit Diagram



Recommended PCB Layout



Series	Type*	Height*	Operating Force*	Packaging*
508	2 2 SMT (mit reduziertem Platzbedarf) SMT (Reduced Space) 3 Standard SMT Standard SMT	1 1 H=4,3mm 2 H=5,0mm	40 30 160g±50 (braun) 160g±50 (brown) 40 260g±50 (rot) 260g±50 (red) 50 320g±80 (lachsfarben) 320g±80 (salmon) 70 520g±130 (gelb) 520g±130 (yellow)	TR ST TR

Lieferformen / Packaging Options:

ST In Stangen / In tubes
TR Tape & Reel / Tape & Reel

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* This is an **order example** - please replace by your specifications.

Empfehlungen für das Wellenlötverfahren

Recommendations for Wave Soldering

Die Bauteile sollten bei einer Lötbadtemperatur von 260°C in max. 5 Sekunden verlötet werden.
Items should be soldered at a solder temperature of 260°C in 5 seconds max.

Empfohlenes Wellenlötprofil:
Recommended wave soldering profile:



Informationen zum kurzen Reflow-Lötverfahren

Fast Profile Reflow Soldering Information

Reflow-Löttempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	120-150s
Temperatur Lötbereich T_L	230°C
Verweildauer oberhalb T_L	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1,5°C / s
Höchsttemperatur T_P	260°C max.
Dauer Höchsttemperatur	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 4,5min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	120-150s
Soldering Range Temperature T_L	230°C
Duration above T_L	60s max.
Ramp-Up Rate $T_{Smax} - T_P$	max. 1.5°C / s
Peak Temperature T_P	260°C max.
Duration Peak Temperature	5-10s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	3°C / s
Duration 25°C - Peak Temp. T_P	Max. 4.5min